### 501936690 05/29/2012

#### PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date	
Bo-I LEE	03/12/2012	
Huang Soon KANG	03/14/2012	
Chi-Ming YANG	03/14/2012	
Chin-Hsiang LIN	03/14/2012	

## RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	
City:	Hsinchu	
State/Country:	TAIWAN	
Postal Code:	300	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13420366

#### **CORRESPONDENCE DATA**

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**Total Attachments: 1** 

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PATENT REEL: 028283 FRAME: 0063 OP \$40.00 1342036

# ASSIGNMENT

In consideration of the premises and of	ther good and valuable consideration	in hand paid,	the receipt and	sufficiency of
which is hereby acknowledged, the undersigned				

1) Bo-I LEE

4) Chin-Hsiang LIN

- 2) Huang Soon KANG
- 3) Chi-Ming YANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

#### TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No.

#### 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

## MANUFACTURE AND METHOD OF MAKING THE SAME

- (a) for which an application for United States Letters Patent was filed on 2012-03-14 , and identified by United States Patent Application No. 13/420, 366 ; or
- (b) for which an application for United States Letters Patent was executed on \_\_\_\_\_\_

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Bo-I Lee
Name: Bo-I LEE
2) Hay have: Huang Soom KANG
3) Cli - Ming Yang
Name: Chi-Ming YANG
4)
Name: Chin-Hsiang LIN

ChinAll Chin-Hsiang LIN

Date:

Date:

Date:

Date:

Date:

Date:

Date:

Date: 2012.3.14.

PATENT REEL: 028283 FRAME: 0064

RECORDED: 05/29/2012